

## **AMENDMENTS TO THE CLAIMS**

Please amend the claims as indicated below.

1. (Currently amended) A cooling apparatus for a computer comprising:
  - a conductive base plate configured to be installed over a CPU and to transfer heat therefrom;
  - a heat conductor thermally coupled to the base plate adapted to carry heat transferred to the base plate by the CPU away from the base plate;
  - a heat sink thermally coupled to the heat conductor for dissipating heat carried by the heat conductor;
  - a fan for dispersing heat transferred to the heat sink, wherein the fan is configured to direct an airflow over a power supply installed within the computer to remove heat therefrom; and
  - a housing adapted to substantially enclose ~~for~~ the heat sink and the fan and configured to be installed adjacent to a window in a computer chassis such that the fan can direct airflow through the heat sink and out the window.
2. (Original) The apparatus of claim 1, wherein the computer chassis is for a small form factor computer.
3. (Original) The apparatus of claim 1, wherein the heat conductor comprises one or more heat pipes.
4. (Original) The apparatus of claim 3, wherein the thermal conductor comprises a plurality of heat pipes, each heat pipe connected to the heat sink through a hole to facilitate heat exchange therebetween.
5. (Original) The apparatus of claim 3, wherein the heat pipes contain at least one of: a metal mesh grid and a liquid for transferring the heat contained within the heat pipe.
6. (Canceled)

7. (Original) The apparatus of claim 1, wherein the fan is configured to face the power supply.

8. (Previously presented) The apparatus of claim 1, wherein the heat sink comprises a plurality of cooling fins.

9. (Previously presented) The apparatus of claim 8, wherein the cooling fins are made of one of: copper and compression molded aluminum.

10. (Original) The apparatus of claim 1, further comprising a computer chassis comprising the window in the computer chassis, a screen over the window, and a second window configured to intake ambient air.

11-12. (Canceled)

13. (New) A method of cooling the interior of a computer chassis including a CPU and a power supply, the method comprising:

transferring heat generated by the CPU to a heat sink through a base member installed adjacent to the CPU and a cooling pipe connected to the heat sink;  
drawing airflow into the chassis over the heat sink through a fan installed adjacent to a first window in the chassis, the heat sink and fan substantially enclosed in a housing secured to the chassis; and  
directing airflow over the power supply and out a second window in the chassis.

14. (New) The apparatus of claim 1, wherein the housing is configured to snap over and secure the heat sink and fan to the chassis.

15. (New) A cooling apparatus for a computer chassis, the apparatus comprising:  
a base plate installed adjacent to a CPU for removing heat generated therefrom;  
a heat sink coupled to the base plate through a heat pipe, the heat sink for dissipating heat from the base plate; and

a fan for drawing air through a first window in the chassis and over the heat sink and power supply to remove heat therefrom, the air to be dispelled out a second window in the chassis installed perpendicular to the first window, wherein the CPU and power supply are stored in a single, unpartitioned chamber of the chassis.

16. (New) The apparatus of claim 15 further comprising a housing adapted to cover the heat sink and fan and configured to be installed adjacent to the first window.